



Material Content Data Sheet



Sales Product Name		BSC030N08NS5		Issued		4. July 2019		
MA#		MA003218866						
Package		PG-TDSON-8-50		Weight*		107.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.517	1.41	1.41	14133	14133
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		127	
	non noble metal	zinc	7440-66-6	0.055	0.05		508	
	non noble metal	iron	7439-89-6	1.090	1.02		10156	
wire	non noble metal	copper	7440-50-8	44.271	41.23	42.31	412385	423176
	noble metal	gold	7440-57-5	0.042	0.04	0.04	392	392
	encapsulation	organic material	carbon black	1333-86-4	0.083	0.08		777
	plastics	epoxy resin	-	3.835	3.57		35727	
	inorganic material	silicondioxide	60676-86-0	37.771	35.18	38.83	351835	388339
leadfinish	non noble metal	tin	7440-31-5	1.264	1.18	1.18	11772	11772
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	270	270
solder	noble metal	silver	7440-22-4	0.052	0.05		480	
	non noble metal	tin	7440-31-5	0.103	0.10		960	
	non noble metal	lead	7439-92-1	1.907	1.78	1.93	17768	19208
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		43	
	non noble metal	zinc	7440-66-6	0.018	0.02		171	
	non noble metal	iron	7439-89-6	0.368	0.34		3425	
	non noble metal	copper	7440-50-8	14.930	13.91	14.27	139071	142710
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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